

Forward-looking Statement

- Information included in this presentation that are not historical in nature are "forward looking statements". C Sun cautions readers that forward looking statements are based on C Sun's reasonable knowledge and current expectations and are subject to various risks and uncertainties.
- Actual results may differ materially from those contained in such forward looking statements for a variety of reasons including without limitation, risks associated with demand and supply change, manufacturing and supply capacity, design win, time to market, market competition, industrial cyclicity, customer's financial condition, exchange rate fluctuation, legal actions, amendments of the laws and regulations, global economy change, natural disasters, and other unexpected events which may disrupt C Sun's business and operations.
- Accordingly, readers should not place reliance on any forward looking statements. Except as required by law, C Sun undertakes no obligation to update any forward looking statement, whether as a result of new information, future events, or otherwise.



C Sun Mfg Ltd.

SinoPac Securities 2025.4.16



Business Philosophy- ALL WIN



G2C+

合力共創 同行致遠

Well-intentioned motives
lead careers to success

---From 『Heart』 Inamori Kazuo

The Alliance Members: 1700+



R&D personnel: 560+

R&D personnel account for 32.5%



Since 1966

Since 1978

Since 1978

***c sun* 志聖**

Thermal (熱)
Bonder (壓合)
Lamination (貼膜)
Peeling (撕膜)
UV/Plasma (光/電漿)

GPM 均豪精密

AOI (檢測)
Metrology (量測)
Grinding (研磨)
Polishing (拋光)

GMM 均華精密

Die Attach (黏晶)
Chip Sorter (揀晶)
Auto Jig Saw (切單挑揀)

Core Technologies & Alliance Synergy

Foundry 2.0

Downstream
Integration

Info
cWoS
Solc

Advanced Packaging

OSAT
Upstream
Development

MEM

FOCOS

SiP

PLP

FC → WLCSP → 2.5D

c sun Bonder
Lamination
Peeling

GPM AOI
Metrology
Grinding
Polishing

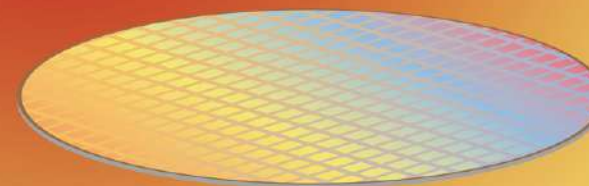
GMM Die Attach
Chip Storter
Auto Jid Saw

Advance Packaging

IC Substrate 、 HBM Packaging 、 2.5/3DIC



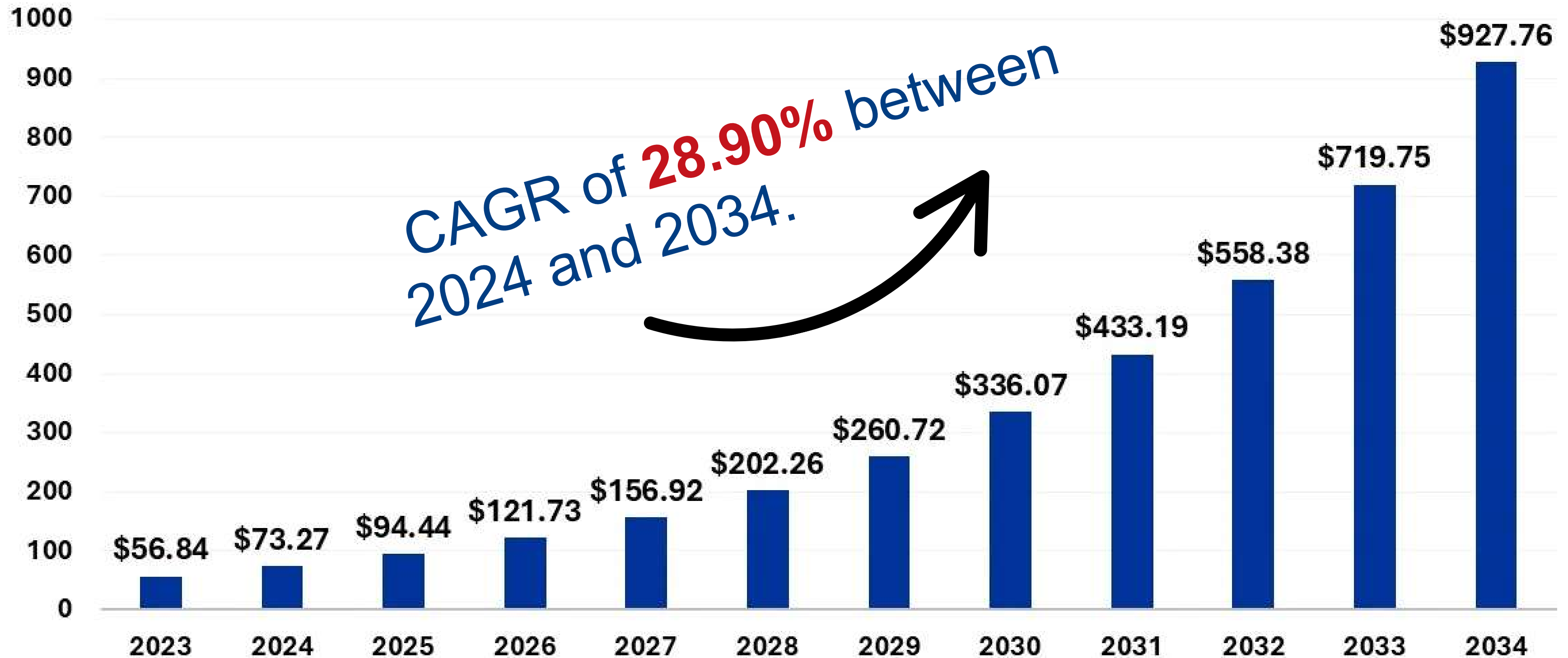
GT2C+
T STRATEGY ALLIANCE



c sun GPM

Foundry
Reclaim wafer

Artificial Intelligence (AI) Chip Market Size 2023 to 2034 (USD Billion)



Taiwan's West Golden Corridor: **AI Chips**

The Shining Diamond Chain of Advanced Packaging Processes

Taiwan's Market Share in
Packaging and Testing by Value

58.6 %

Taiwan's Market Share in
Wafer Manufacturing by Value

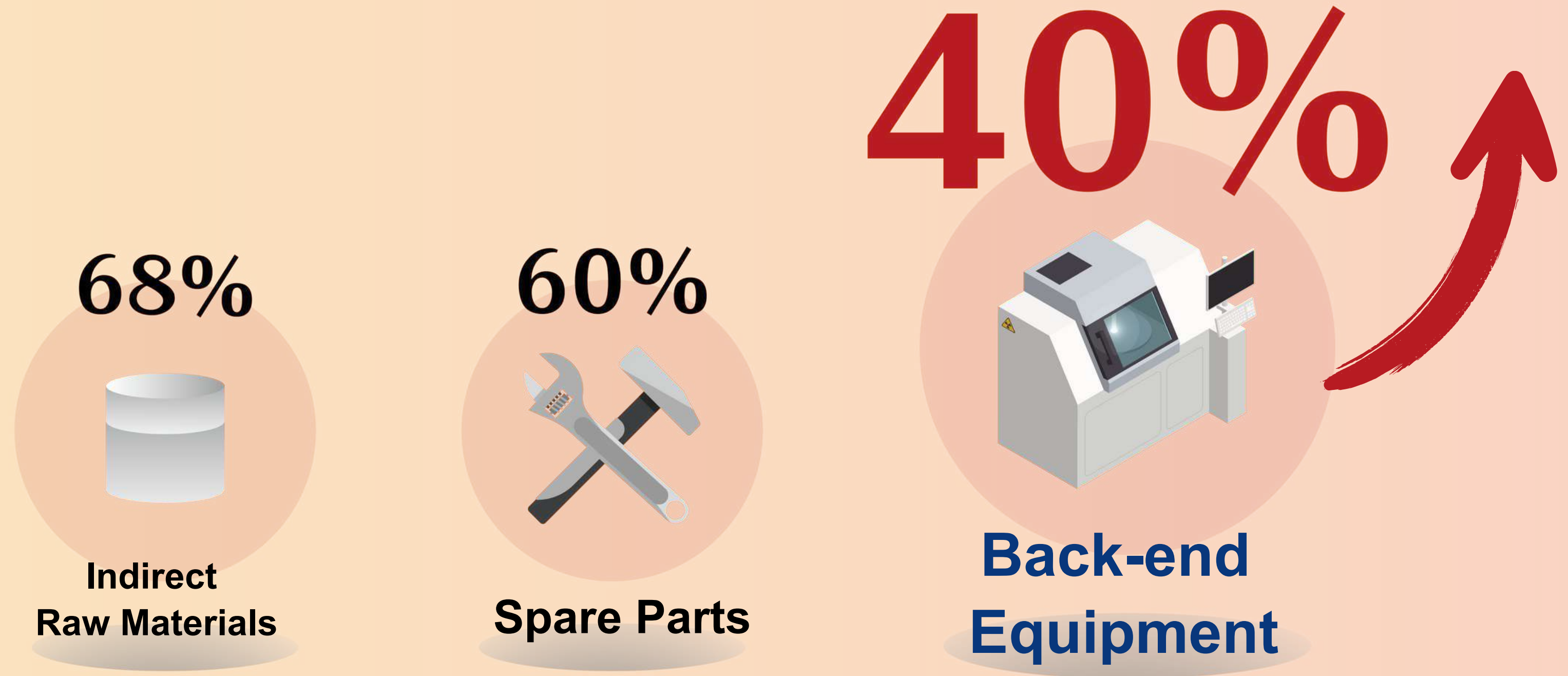
76.8 %



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TSMC is committed to increase local procurement

Vision for 2030



Company Introduction



2023、2024
TSMC Award

Employee and Family
Shareholding >40%

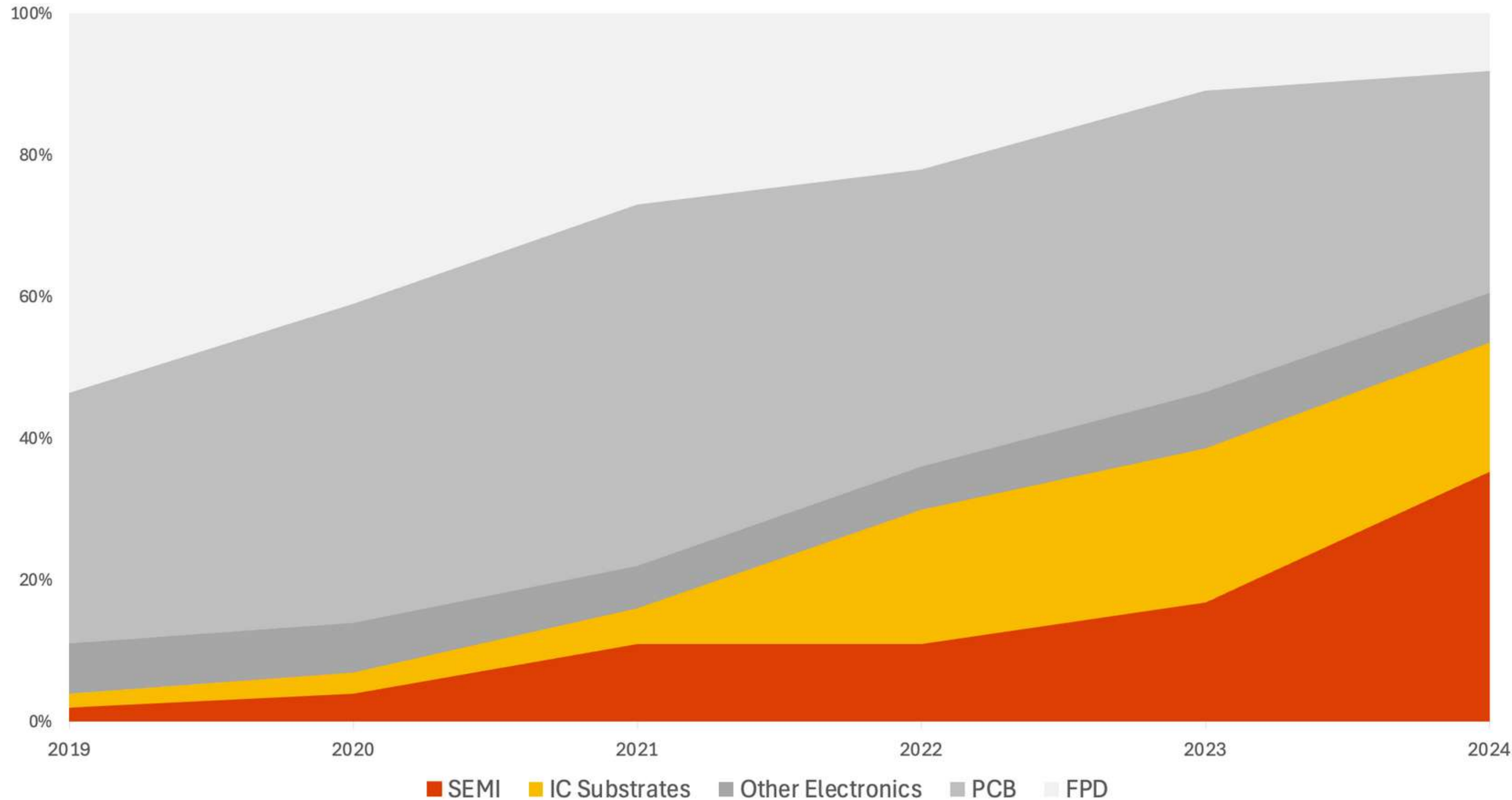


Establishment: 1966.9.28
Capital: NT\$1.56 billion
Chairman: Morrison Liang
President: Frank Liang

Financial Review

<i>Selected Items from Statements of Comprehensive Income</i> <i>(In NT\$ millions unless otherwise noted)</i>	2025 Q1	2024	2023	YoY 同比
Revenue-Consolidated	1,309	4,818	3,626	32.9%
Gross Margin%		41.2%	41.5%	-0.3ppts
Operating Expense		(1,347)	(1,104)	22%
Operating Expense%		28.0%	30.4%	-2.4ppts
Operating Margin%		13.2%	11.1%	+2.1ppts
Non-Operating Items		344	181	90%
Net Income Attributable to Shareholders of the Parent Company	150	719	486	48%
Net Profit Margin%	11.5%	14.9%	13.4%	+1.5ppts
EPS (NT\$D)	1	4.8	3.12	54%
ROE		16.60%	14.11%	-

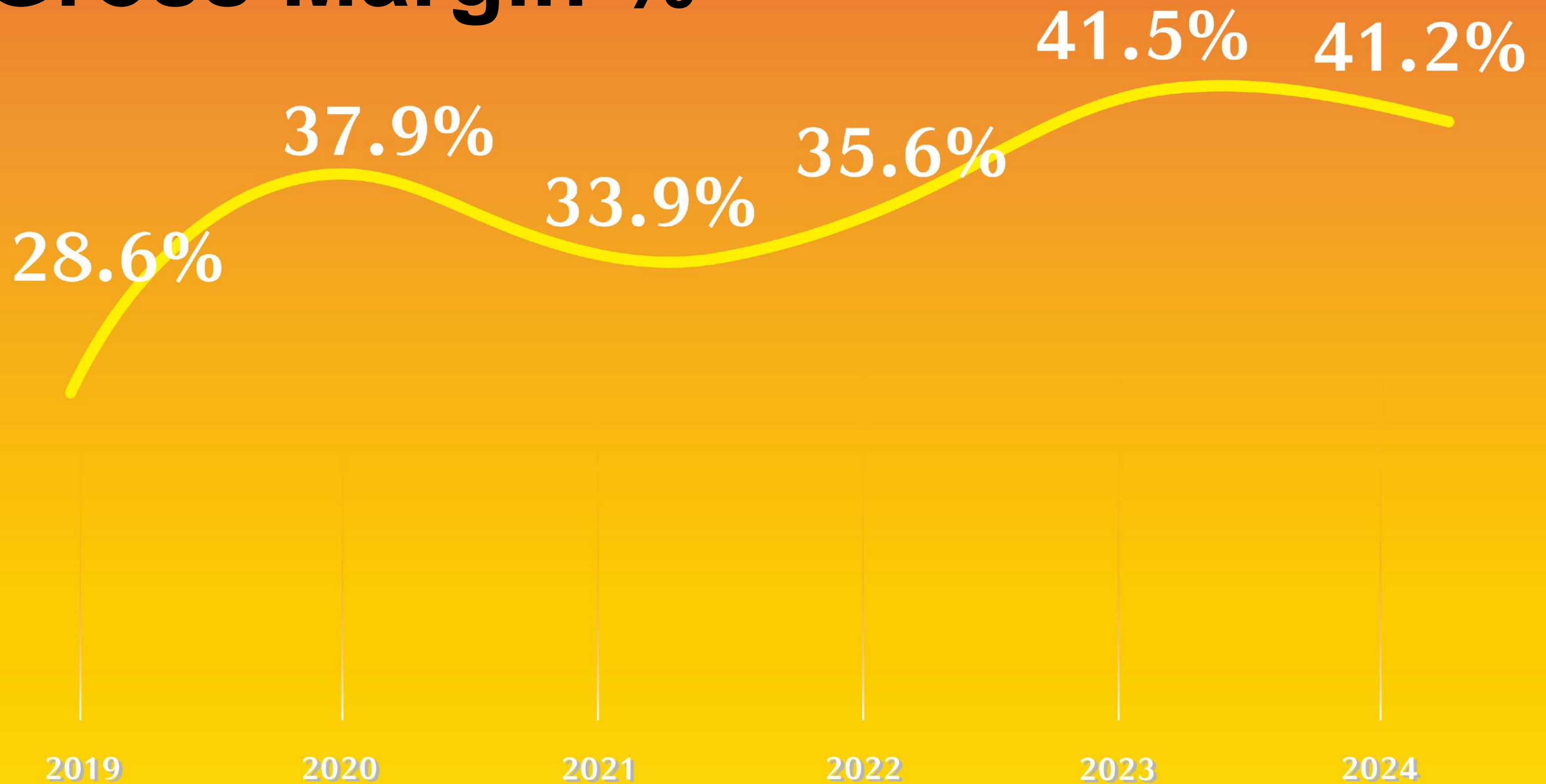
Revenue Composition



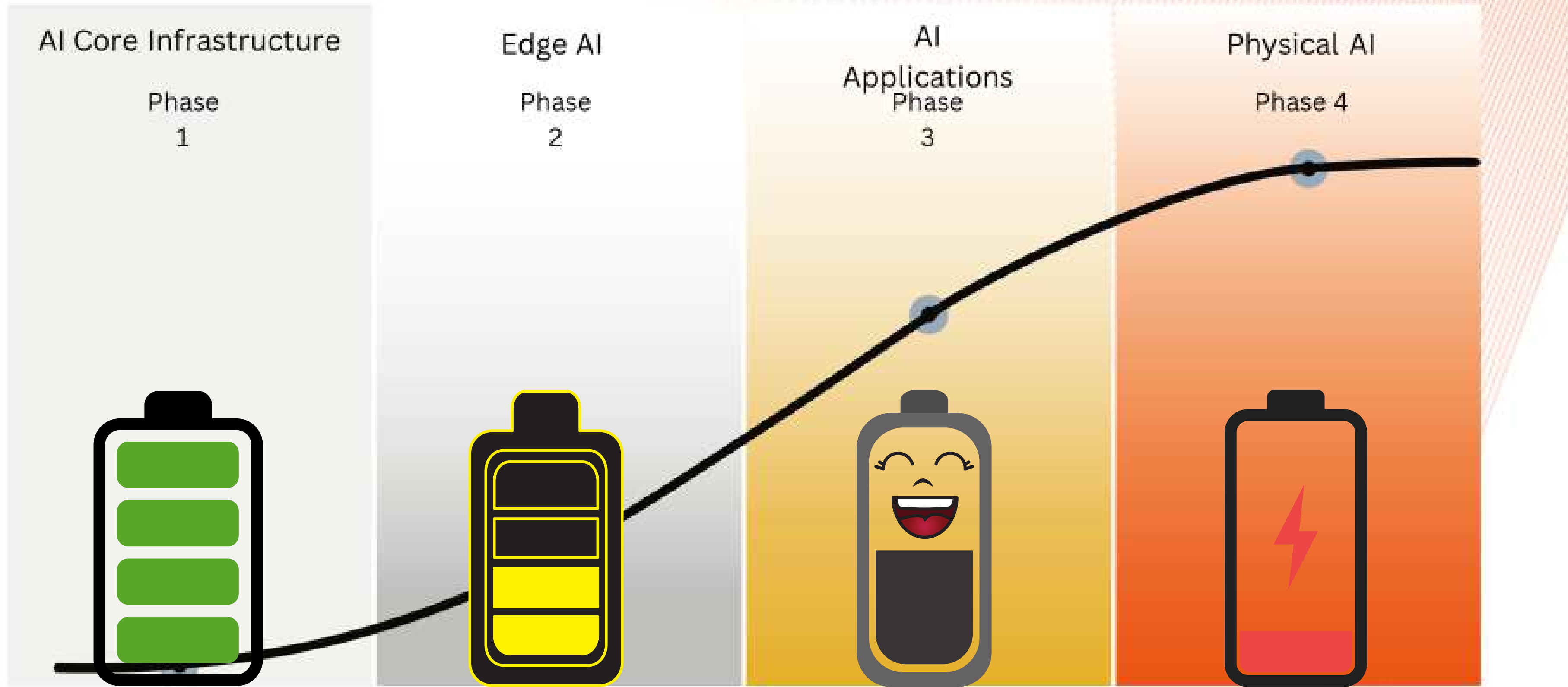
SEMI~35%



Gross Margin %



Coatue Framework for AI S-Curve



AI 聚焦

HBM

oS

LPO

Assembly

IC Substrate

CoW

SoC/SolC

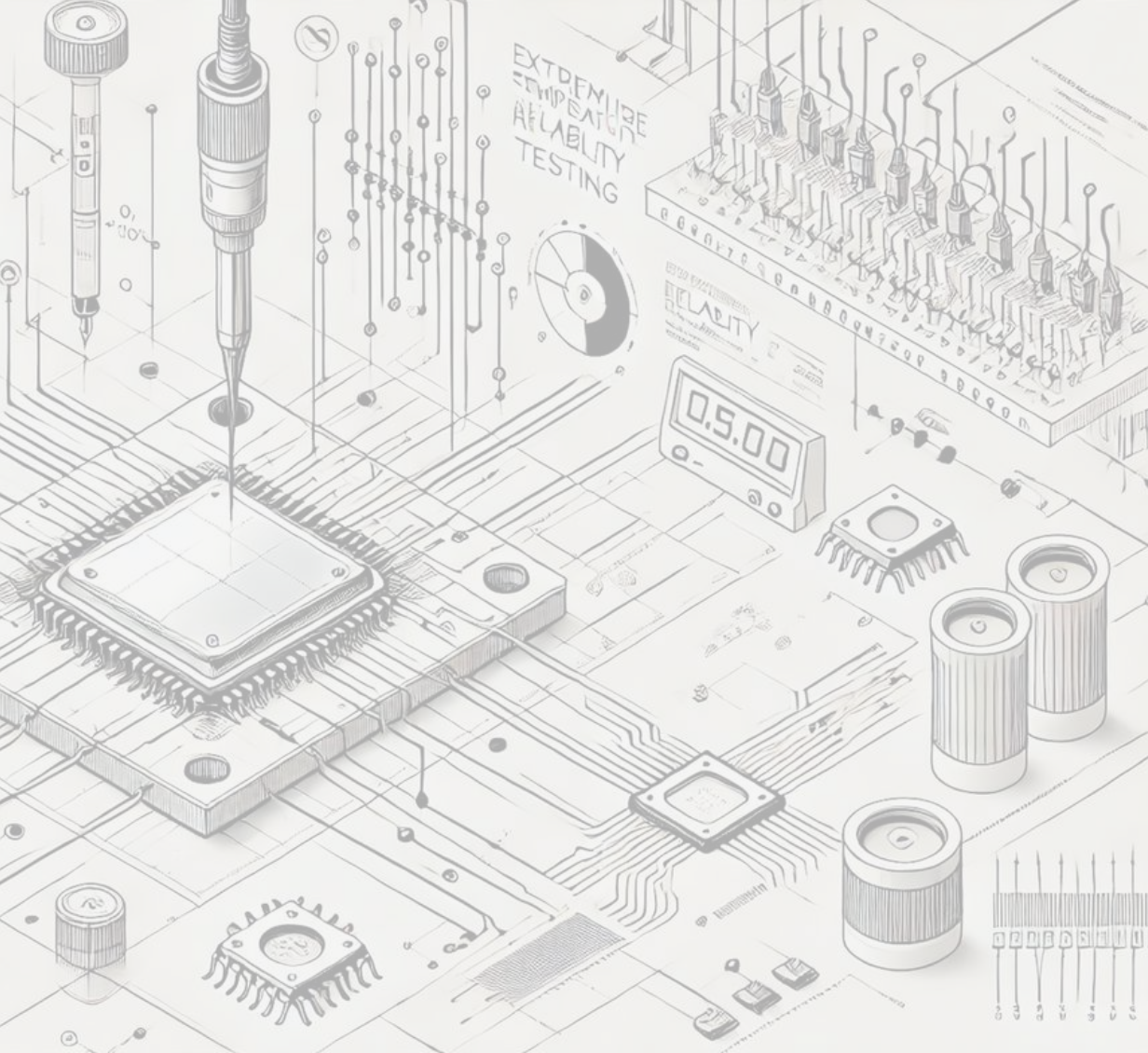
CPO

Test

Mother Board

2024

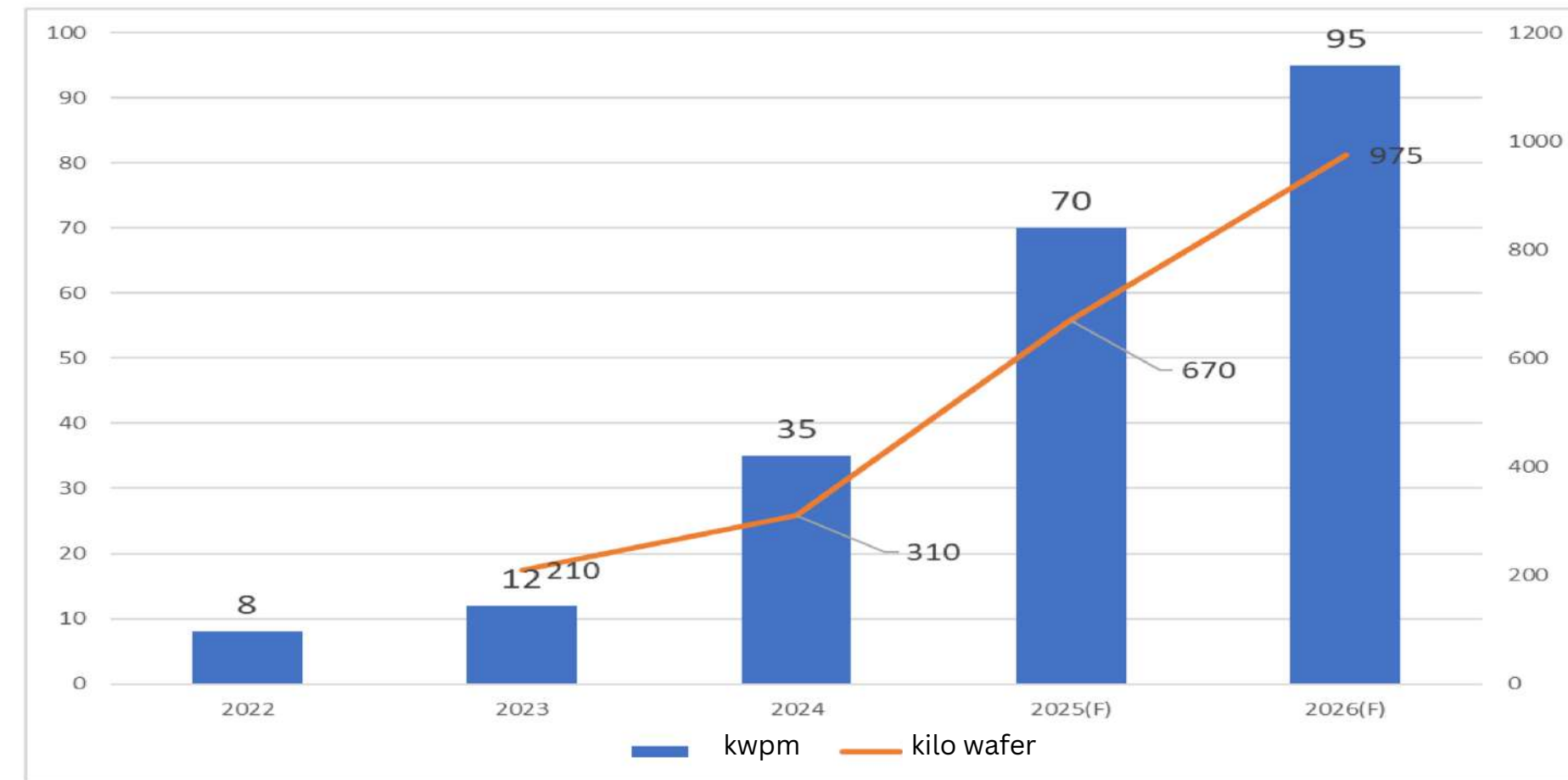
>50%



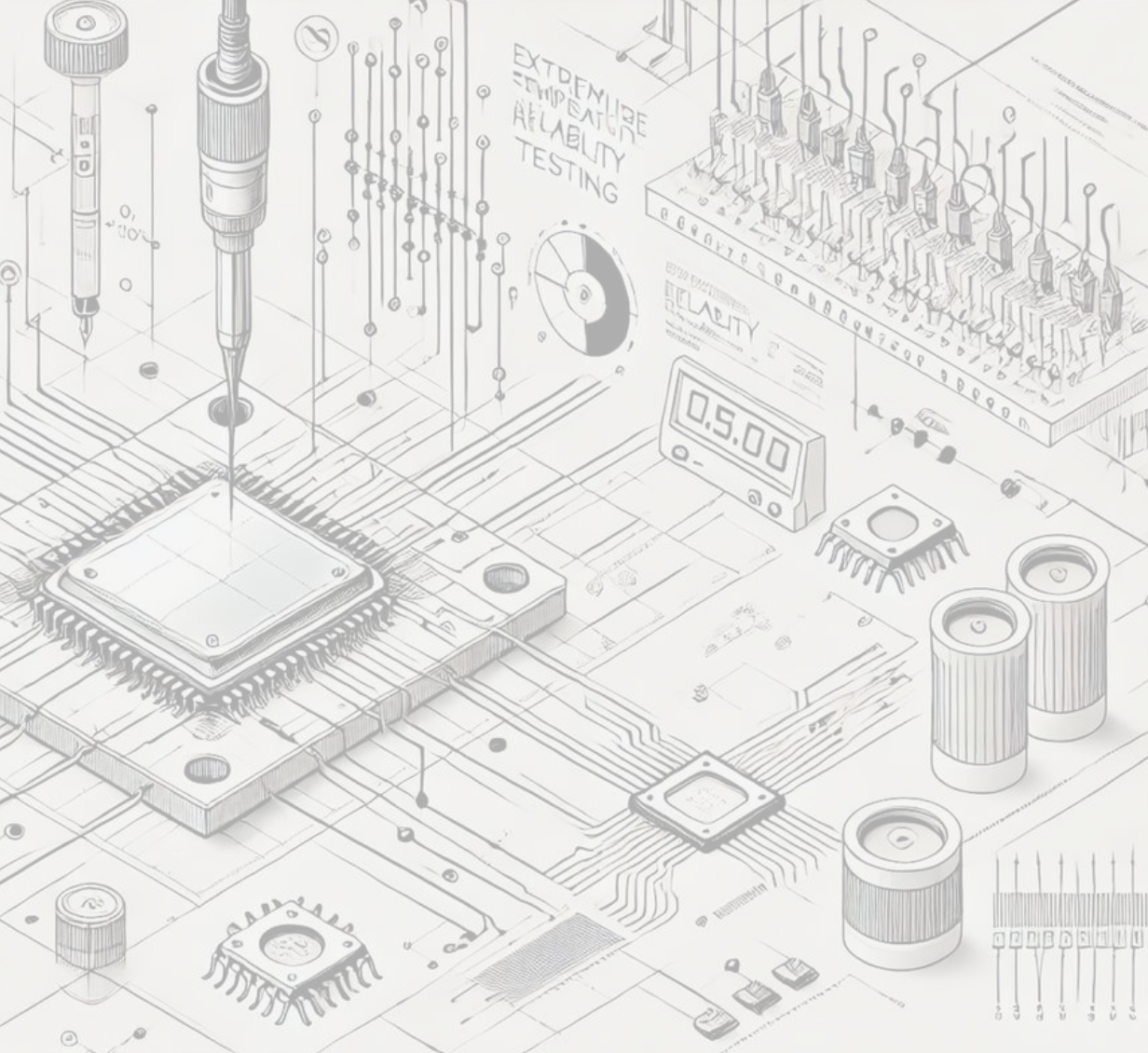
Dynamics of CoWoS Demand and Production Capacity

- DeepSeek Phenomenon.
- CoWoS Process Remains Primary Process for AI Chips.
- **Clients' Capacity Expansion Drives Equipment Demand**
- Additional Process Stations to Boost Equipment Penetration.

Prospects for Equipment in Leading Customers' Advanced Packaging Processes



資料來源：兆豐國際投顧預估



FoPLP and CoPos Dynamics

Glass



310x310

AI晶片

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現況應用:

PMIC、RF

Glass/Metal 對應基材

700 x 700

600 x 600

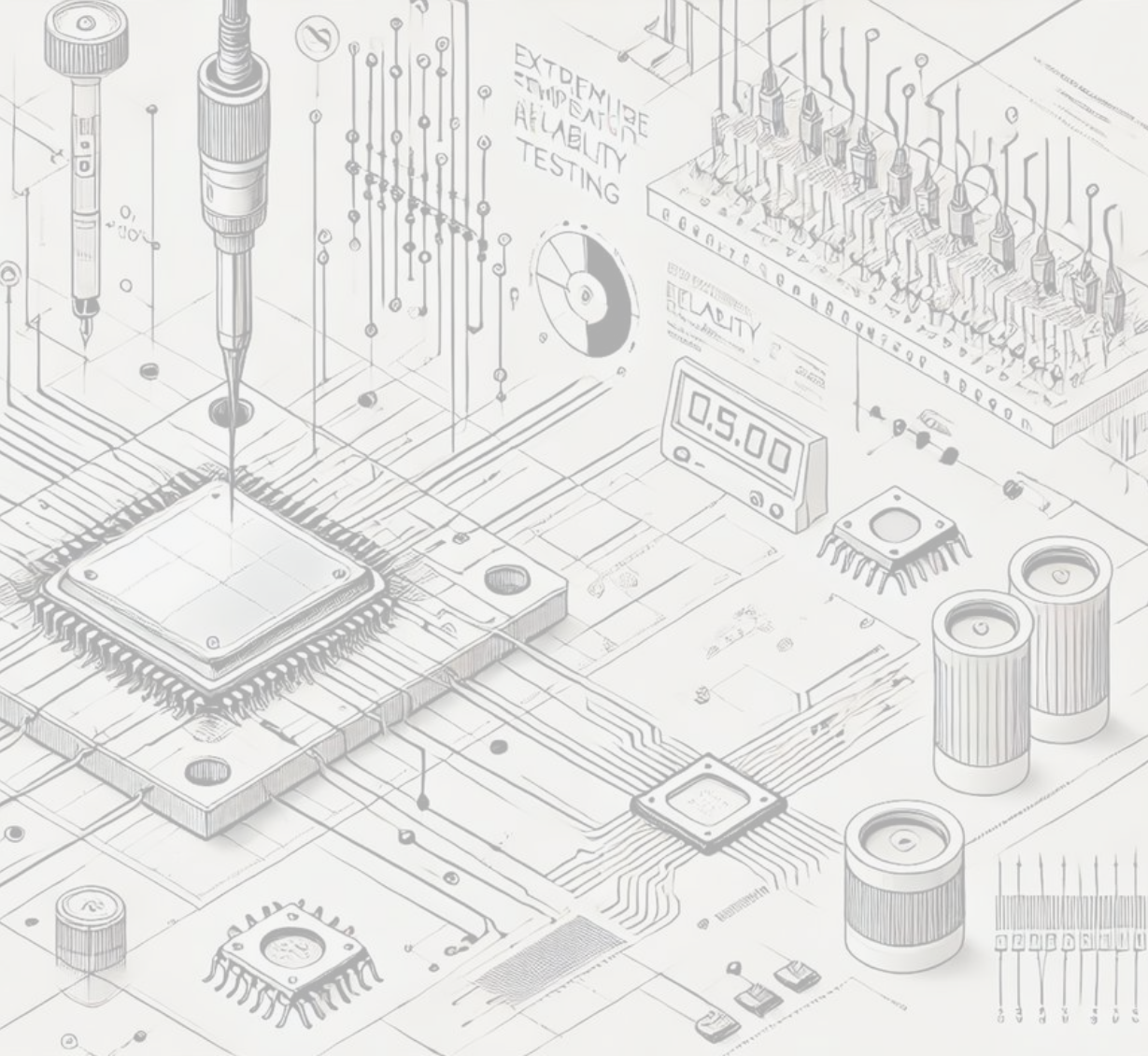
510 x 515

300 x 300

Prospects for
Equipment in Leading
Customers' Advanced
Packaging Processes

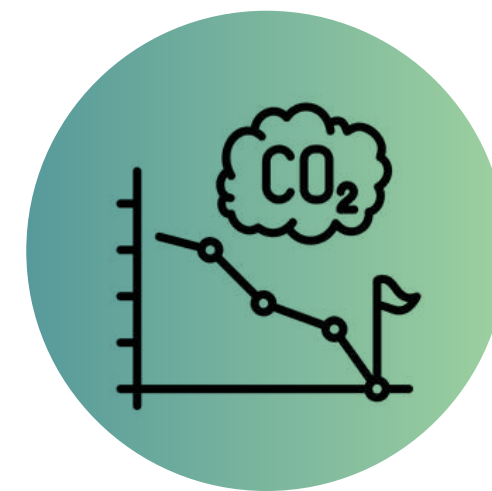
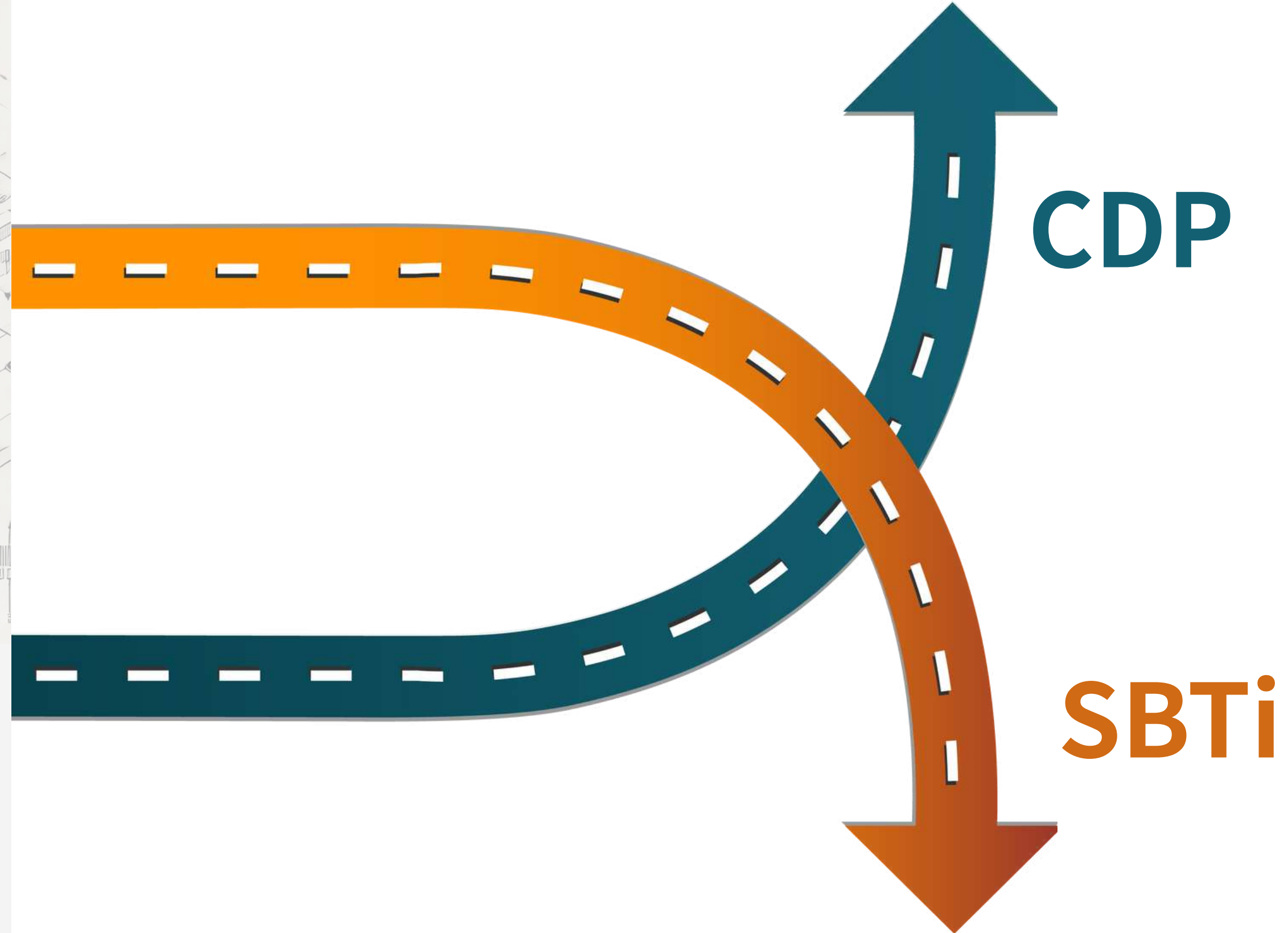
Internationalization (Grand Voyage)





Our commitment to
Sustainability and
Disclosure

Setting ISO 14067
Certification Targets



*c sun*志聖 Exhibition Preview

touch
TAIWAN 系列展
台北南港展覽館一館四樓

04/16-18, 2025

10:00~17:00

智慧顯示展 | 智慧製造展 | 電子生產製造設備展

敬邀您蒞臨攤位洽詢

4FM719

各界產業先進 您好

感謝您一直以來的鼓勵與愛護，

您的信賴與支持是我們成長茁壯的原動力。

誠摯地邀請您蒞臨4FM719攤位，

洽詢全方位智能化解決方案。



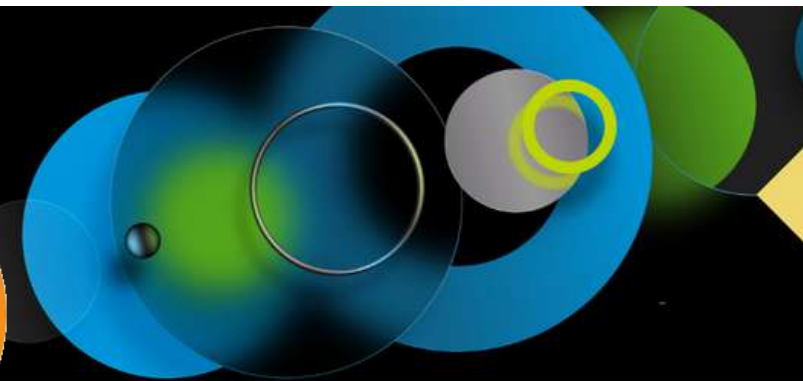
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GPM 均豪精密

GMM 均華精密

SEMICON[®] 30 YEARS
SOUTHEAST ASIA Special Edition
MAY 20-22, 2025 10:00~17:00 SGT
SANDS EXPO & CONVENTION CENTRE
SINGAPORE



BASEMENT 2
B1524

We sincerely invite you to visit our exhibition booth for inquiries.
Our team will be there to introduce our comprehensive smart solutions, aiming to enhance production line efficiency and create business opportunities.

G2C+
T STRATEGY ALLIANCE

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GPM 均豪

GMM 均華



The background is a detailed, isometric illustration of various electronic components and tools, rendered in a light orange color against a darker orange background. The components include integrated circuits, capacitors, resistors, and connectors. Tools like screwdrivers and a soldering iron are also visible. The overall theme is electronics and manufacturing.

Csun

A **G2C+** Alliance Company

Thank you for your attention
